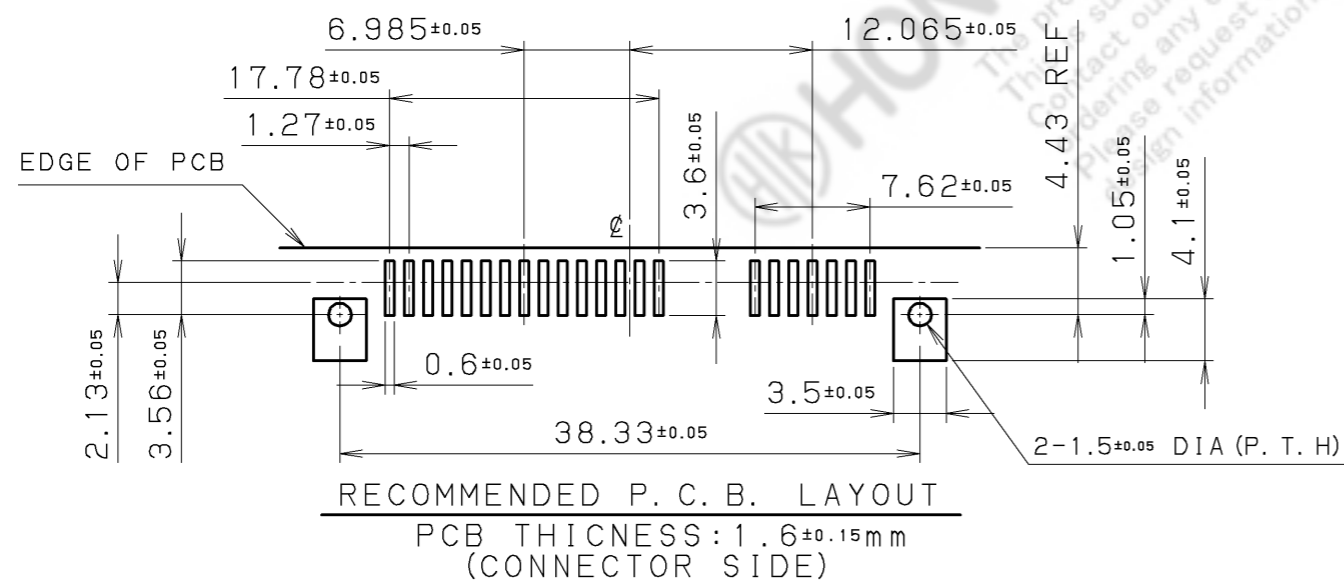
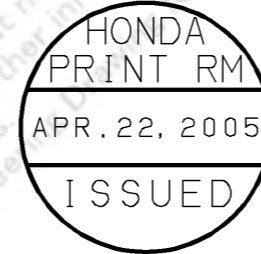


SECTION A-A'
SCALE 5:1

NOTE 1. CONTACT PLATING:
CONTACT AREA: GOLD 0.2 μm MIN.
TERMINATION AREA: TIN/COPPER 2 μm MIN.
ALL OVER NICKEL UNDERPLATED.
2. CONNECTOR PIN ASSIGNMENTS

•S1 - GROUND	•P1 - 3.3V
•S2 - A+	•P2 - 3.3V
•S3 - A-	•P3 - 3.3V
•S4 - GROUND	•P4 - GROUND
•S5 - B-	•P5 - GROUND
•S6 - B+	•P6 - GROUND
•S7 - GROUND	•P7 - 5V
	•P8 - 5V
	•P9 - 5V
	•P10 - GROUND
	•P11 - GROUND
	•P12 - GROUND
	•P13 - 12V
	•P14 - 12V
	•P15 - 12V

3. CONTACT COPLANARITY IS 0.1mm MAX.



△				3	BOARD LOCK	COPPER ALLOY	2	TIN	
△				2	CONTACT	COPPER ALLOY	22	SEE NOT#1	
△	Aug.22.2005	K. Kuwana	Change shape and material	1	INSULATOR	LCP △	1		E4711 BLACK
LTR.	DATE	BY	REV. DESCRIPT	No.	PART NAME	MATERIAL	QTY	FINISH	NOTE
	APR.28.2005		2 / 1		3RD. A. P				HONDA TSUSHIN KOGYO CO., LTD.
	APP. DATE&REV.								
DR.	DE.	CHK.	CHK.	APP.	NAME	SERIAL ATA VERTICAL HOST RECEPTACLE CONNECTOR			
K. KUWANA	K. KUWANA	K. KASAI		K. OHNISHI	PART NO.	HSA-SP22SFYAG			REV. 1A